



### 20V P-CHANNEL ENHANCEMENT MODE MOSFET POWERDI<sup>®</sup>

### **Product Summary**

V <sub>(BR)DSS</sub>	R <sub>DS(ON)</sub>	I <sub>D</sub> T <sub>C</sub> = +25°C
	$1.9 m\Omega @ V_{GS} = -10V$	-60A
-20V	$2.4 m\Omega$ @ $V_{GS} = -4.5 V$	-60A
	$3.8 \text{m}\Omega$ @ $V_{GS} = -2.5 \text{V}$	-60A

## **Description**

This new generation P-Channel Enhancement Mode MOSFET is designed to minimize R<sub>DS(ON)</sub> and yet maintain superior switching performance. This device is ideal for use in notebook battery power management and load switch.

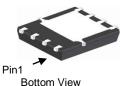
### **Applications**

Switch

### POWERDI5060-8





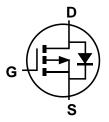


### **Features**

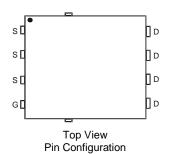
- Thermally Efficient Package-Cooler Running Applications
- High Conversion Efficiency
- Low R<sub>DS(ON)</sub> Minimizes On State Losses
- <1.1mm Package Profile Ideal for Thin Applications
- Lead-Free Finish; RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- Qualified to AEC-Q101 Standards for High Reliability

## **Mechanical Data**

- Case: POWERDI5060-8
- Case Material: Molded Plastic, "Green" Molding Compound; UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminal Finish Matte Tin Annealed over Copper Leadframe; Solderable per MIL-STD-202, Method 208@3
- Weight: 0.097 grams (Approximate)



Internal Schematic



Ordering Information (Note 4)

Part Number	Case	Packaging
DMP2002UPS-13	POWERDI5060-8	2,500 / Tape & Reel

Notes:

- 1. EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant. All applicable RoHS exemptions applied.
- 2. See http://www.diodes.com/quality/lead\_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green"
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and

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4. For packaging details, go to our website at http"//www.diodes.com/products/packages.html.

## **Marking Information**



⊃¦¦ =Manufacturer's Marking P2002US = Product Type Marking Code YYWW = Date Code Marking YY = Last Digit of Year (ex: 14 = 2014) WW = Week Code (01 to 53)



# **Maximum Ratings** (@ $T_A = +25^{\circ}C$ , unless otherwise specified.)

Characteristic	Symbol	Value	Units		
Drain-Source Voltage	V <sub>DSS</sub>	-20	V		
Gate-Source Voltage	V <sub>GSS</sub>	±12	V		
Continuous Dunin Coursett V 40V/(Note 5)	Steady State (Note 8)	$T_C = +25$ °C $T_C = +70$ °C		-60 -60	А
Continuous Drain Current, V <sub>GS</sub> = 10V (Note 5)	t<10s	$T_A = +25$ °C $T_A = +70$ °C	l <sub>D</sub>	-42 -33.5	А
Pulsed Drain Current (10µs pulse, duty cycle = 1%)	I <sub>DM</sub>	-100	Α		
Continuous Body Diode Forward Current (Note 5)	Steady State (Note 8)	T <sub>C</sub> = +25°C	Is	-60	А
Commission Deal Product Commission (Note 6)	t<10s	$T_A = +25$ °C	13	-5.6	Α
Avalanche Current, L = 0.1mH	I <sub>AS</sub>	-37	А		
Avalanche Energy, L = 0.1mH	E <sub>AS</sub>	69.8	mJ		

# **Thermal Characteristics**

Characteristic	Symbol	Value	Units	
Total Dayor Dissination (Note 5)	Steady State		2.3	W
Total Power Dissipation (Note 5)	t<10s	$P_{D}$	6.25	
Thermal Desistance Junction to Ambient (Note 5)	Steady State		55	°C/W
Thermal Resistance, Junction to Ambient (Note 5)	t<10s	$R_{ heta JA}$	20	
Total Power Dissipation (Note 5)	Steady State	P <sub>D</sub>	104	W
Thermal Resistance, Junction to Case (Note 5)		R <sub>eJC</sub>	0.9	°C/W
Operating and Storage Temperature Range		T <sub>J</sub> , T <sub>STG</sub>	-55 to +150	°C

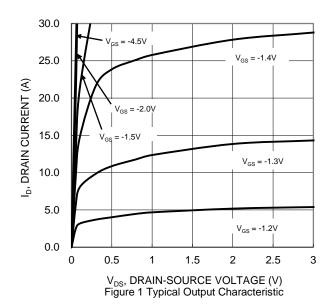


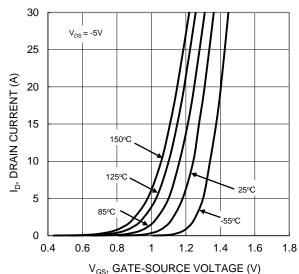
### Electrical Characteristics (@TA = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition	
OFF CHARACTERISTICS (Note 6)							
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	-20	_	_	V	$V_{GS} = 0V, I_D = -250\mu A$	
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	_	_	-1	μA	$V_{DS} = -20V, V_{GS} = 0V$	
Gate-Source Leakage	I <sub>GSS</sub>	1	_	±100	nA	$V_{GS} = \pm 12V, V_{DS} = 0V$	
ON CHARACTERISTICS (Note 6)							
Gate Threshold Voltage	$V_{GS(TH)}$	-0.5	_	-1.4	V	$V_{DS} = V_{GS}, I_{D} = -250 \mu A$	
		-	1.3	1.9		$V_{GS} = -10V, I_D = -25A$	
Static Drain-Source On-Resistance	R <sub>DS(ON)</sub>	1	1.5	2.4	mΩ	$V_{GS} = -4.5V, I_D = -20A$	
		-	2	3.8		$V_{GS} = -2.5V, I_D = -15A$	
DYNAMIC CHARACTERISTICS (Note 7)							
Input Capacitance	$C_{iss}$	1	12826	_			
Output Capacitance	Coss	-	2547	_	pF	$V_{DS} = -10V$ , $V_{GS} = 0V$ f = 1MHz	
Reverse Transfer Capacitance	$C_{rss}$	_	1924	_		1 – 1141112	
Gate Resistance	R <sub>G</sub>	0.9	4.2	6.6	Ω	$V_{DS} = 0V$ , $V_{GS} = 0V$ , $f = 1MHz$	
Total Gate Charge (V <sub>GS</sub> = -10V)	$Q_g$	1	476	585		V <sub>DS</sub> = -10V, I <sub>D</sub> = -20A	
Total Gate Charge (V <sub>GS</sub> = -4.5V)	$Q_g$	-	228	282	nC		
Gate-Source Charge	$Q_{gs}$	-	24.8	_	110		
Gate-Drain Charge	$Q_gd$	1	61.9	_			
Turn-On Delay Time	t <sub>D(ON)</sub>	-	14.2	28		$V_{DD} = -10V, V_{GEN} = -4.5V,$ $R_{GEN} = 1\Omega, I_{D} = -10A$	
Turn-On Rise Time	$t_R$	_	35.4	70	ns		
Turn-Off Delay Time	t <sub>D(OFF)</sub>	_	361	578	115		
Turn-Off Fall Time	t <sub>F</sub>	1	224	358			
BODY DIODE CHARACTERISTICS							
Continuous Body Diode Forward Current (Note 5 & 8)	Is	-	_	-60	Α	$T_C = +25$ °C	
Pulse Diode Forward Current	I <sub>SM</sub>	_	_	-100	A		
Diode Forward Voltage	$V_{SD}$	_	-0.58	-1.1	V	$V_{GS} = 0V, I_{S} = -5A$	
Reverse Recovery Time (Note 7)	t <sub>RR</sub>	-	137	219	ns		
Reverse Recovery Charge (Note 7)	Qrr		221	332	nC		
Reverse Recovery Fall Time (Note 7)	ta	-	39	_	ne	$I_F = -10A$ , di/dt = 100A/ $\mu$ s	
Reverse Recovery Raise Time (Note 7)	t <sub>b</sub>	_	98	_	ns		

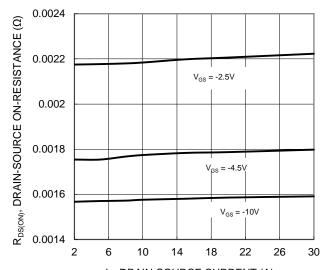
5. Device mounted on FR-4 substrate PC board, 2oz copper, with thermal bias to bottom layer 1inch square copper plate. Notes:

- 6. Short duration pulse test used to minimize self-heating effect.
- 7. Guaranteed by design. Not subject to product testing.
- 8. Package limited.

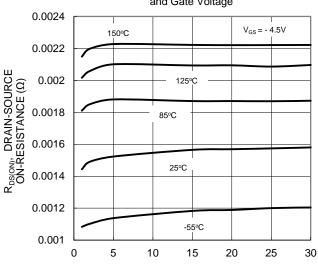








I<sub>D</sub>, DRAIN-SOURCE CURRENT (A) Figure 3 Typical On-Resistance vs. Drain Current and Gate Voltage



 ${\rm I_D},\,{\rm DRAIN\,\,CURRENT(A)}$  Figure 5 Typical On-Resistance vs. Drain Current and Temperature

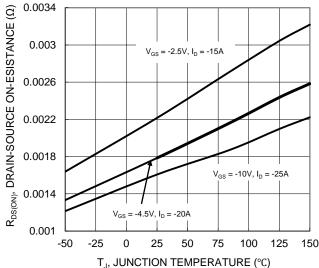
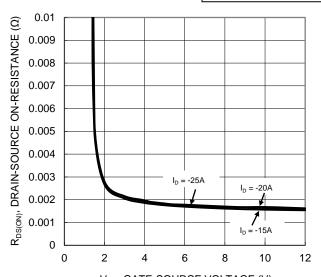
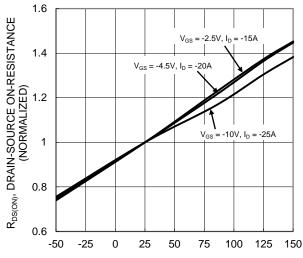


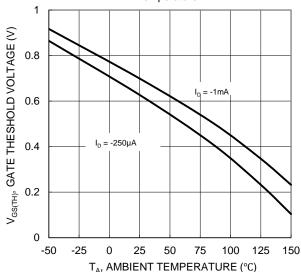
Figure 7 On-Resistance Variation with Temperature



 $V_{GS}$ , GATE-SOURCE VOLTAGE (V) Figure 4 Typical Transfer Characteristic



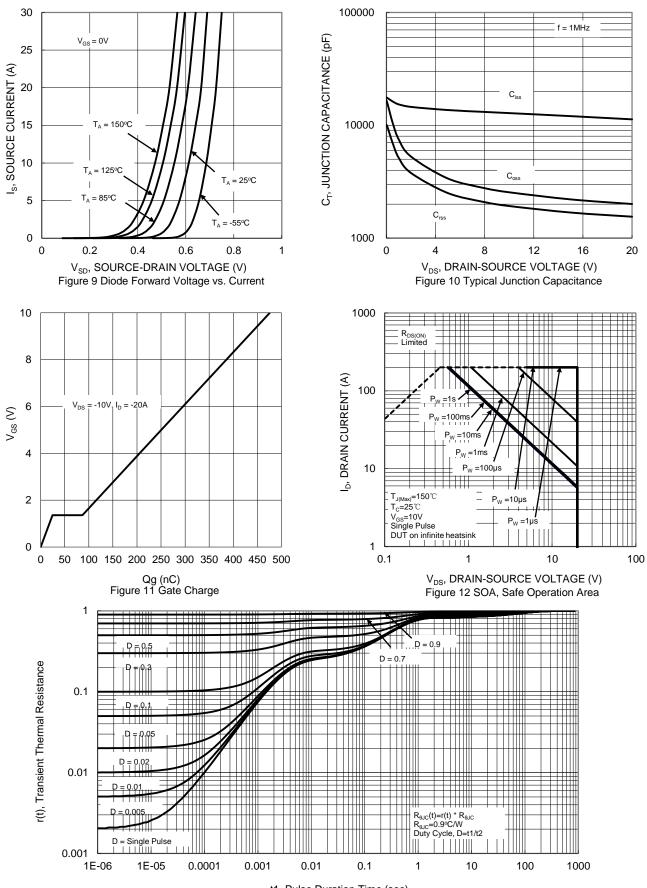
T<sub>J</sub>, JUNCTION TEMPERATURE (°C) Figure 6 On-Resistance Variation with Temperature



 $\rm T_A, \, AMBIENT \, TEMPERATURE \, (^{\circ}C)$  Figure 8 Gate Theshold Variation vs Ambient Temperature





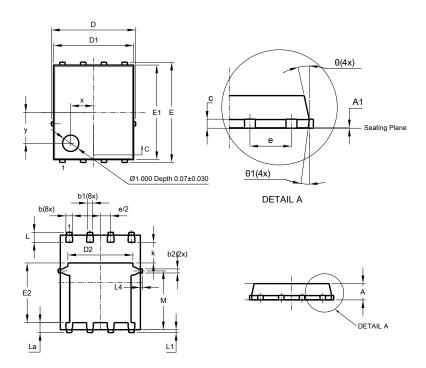


t1, Pulse Duration Time (sec)
Figure 13 Transient Thermal Resistance



# **Package Outline Dimensions**

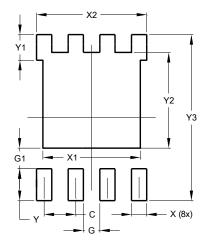
Please see AP02002 at http://www.diodes.com/datasheets/ap02002.pdf for the latest version.



PowerDI5060-8						
(Type K)						
Dim	Min	Max	Тур			
Α	0.90	1.10	1.00			
<b>A</b> 1	0	0.05	0.02			
b	0.33	0.51	0.41			
b1	0.300	0.366	0.333			
b2	0.20	0.35	0.25			
С	0.23	0.33	0.277			
D	5	.15 BS0	2			
D1	4.85	4.95	4.90			
D2	-	-	3.98			
Е	6	6.15 BSC				
E1	5.75	5.85	5.80			
E2	3.56	3.76	3.66			
Е	1.27BSC					
k	-	-	1.27			
L	0.51	0.71	0.61			
La	0.51	0.71	0.61			
L1	0.05	0.20	0.175			
L4	-	-	0.125			
М	3.50	3.71	3.605			
Х	-	-	1.400			
у	-	-	1.900			
θ	10°	12°	11°			
θ1	6°	8°	7°			
All Dimensions in mm						

# **Suggested Pad Layout**

Please see AP02001 at http://www.diodes.com/datasheets/ap02001.pdf for the latest version.



Dimensions	Value (in mm)		
С	1.270		
G	0.660		
G1	0.820		
Х	0.610		
X1	3.910		
X2	4.420		
Υ	1.270		
Y1	1.020		
Y2	3.810		
Y3	6.610		



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